



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : **Confirmation No. 7098**
Keiichi MURAKAMI :
Serial No. 10/538,506 : **Attorney Docket No. 2005-0874A**
Filed June 9, 2005 : **Examiner Thiem D. Phan**
METHOD FOR MANUFACTURING A : Mail Stop: AF
PRINTED WIRING BOARD

DECLARATION UNDER 37 C.F.R. § 1.132

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

I, Keiichi MURAKAMI, the undersigned, do hereby declare and state:

1. That I am a citizen of Japan.
2. That I am the sole inventor of the above-identified application.
3. That I graduated from Kanto Gakuin University in 1987 with a Bachelor's degree in surface engineering.
4. That I have been employed by NODA SCREEN CO., LTD. since 1988, where I hold a position of General Manager.
5. That at the time of filing the present application (hereafter "the 506 application"), the general state of the art in printed circuit board (PCB) design included PCB circuit patterns having a micrometer width.
6. That at the time of filing the '506 application, the general state of the art in PCB design included lines and spaces of approximately 50 micrometers in width in the PCB circuit patterns, and resin particles of approximately 5 micrometers in width.

I further declare that all statements made herein of my own knowledge are true and all statements made on information and belief are believed to be true; and further that these

statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of this application or any patent issuing thereon.

Date: November 14, 2008

Keiichi Murakami

(Signature of Declarant)